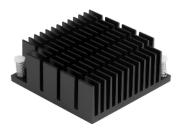


# MODEL: HSB28-606022 | DESCRIPTION: HEAT SINK

#### FEATURES

- BGA design
- top mount
- aluminum alloy



ROHS	
MODEL	

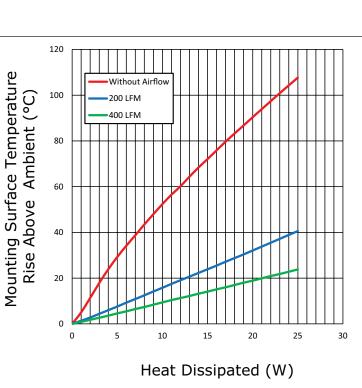
MODEL	thermal resistance <sup>1</sup>				power dissipation <sup>1</sup>
	<b>@ 75°C ΔT, nat</b> conv (°C/W)	<b>@ 1 W,</b> nat conv (°C/W)	<b>@ 1 W,</b> 200 LFM (°C/W)	<b>@ 1 W,</b> 400 LFM (°C/W)	@ 75°C ∆T, nat conv (W)
HSB28-606022	4.74	5.1	1.4	0.9	15.83

Note: 1. See performance curves for full thermal resistance details.

### **PERFORMANCE CURVES**

	1			
	Heatsink Temperature Rise Above Ambient (ΔT = Ths - Ta) (°C)			
Power (W)	Natural Conv.	200 LFM	400 LFM	
0	0	D	O	
1	5.1	1.4	0.9	
3	17.9	4.4	2.7	
5	29.3	7.6	4.6	
7	38.8	10.9	6.5	
9	48.0	14.2	8.4	
11	56.5	17.5	10.4	
13	64.4	20.7	12.2	
15	72.1	23.9	14.1	
17	79.7	27.2	16.0	
19	86.8	30.4	18.0	
21	93.9	33.8	19.9	
23	100.9	37.2	21.8	
25	107.7	40.6	23.8	

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Ths: "hot spot" temperature measured on the heatsink Ta: ambient temperature

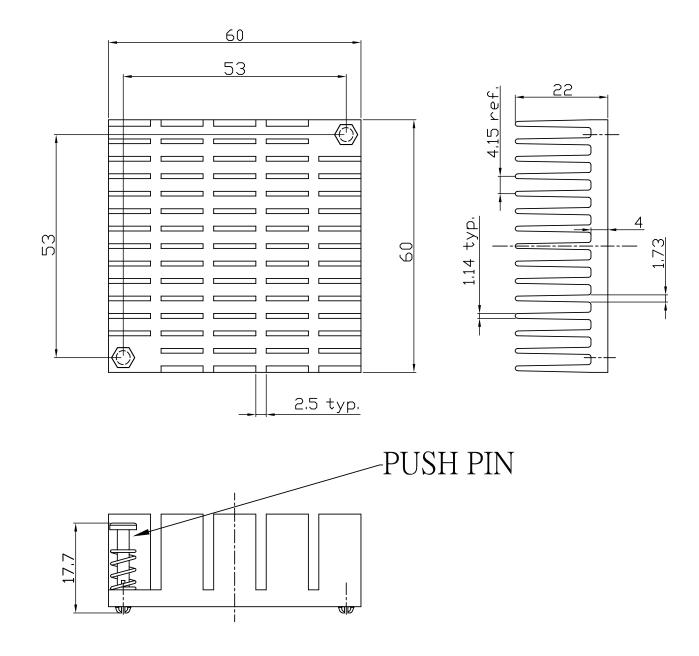
## **MECHANICAL DRAWING**

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units: mm tolerance: ±0.5 mm

MATERIAL	AL 6063-T5
FINISH	black anodized
PUSH PIN	PA66
SPRING	spring steel, nickel plated
WEIGHT	106.5 g

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#### **REVISION HISTORY**

rev.	description	date
1.0	initial release	04/15/2022
1.01	logo, datasheet style update	08/05/2022

The revision history provided is for informational purposes only and is believed to be accurate.

CUI Devices offers a one (1) year limited warranty. Complete warranty information is listed on our website.



CUI Devices reserves the right to make changes to the product at any time without notice. Information provided by CUI Devices is believed to be accurate and reliable. However, no responsibility is assumed by CUI Devices for its use, nor for any infringements of patents or other rights of third parties which may result from its use.

CUI Devices products are not authorized or warranted for use as critical components in equipment that requires an extremely high level of reliability. A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.